

| Ref # | Hits | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|---|---|------------------|---------|------------------|
| L1    | 1    | ("20020194564").PN.   | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR               | OFF     | 2006/01/29 16:39 |
| L2    | 1    | L1 and boundary scan test   | US-PGPUB;<br>USPAT  | ADJ              | OFF     | 2006/01/29 16:39 |
| L3    | 5    | ((("20010194564") or ("6519728") or ("6400173") or ("20020171449") or ("20030006795") or ("20030032263")).PN. | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR               | OFF     | 2006/01/29 16:39 |
| L5    | 5    | ((("6261467") or ("5933709") or ("4835593") or ("6255729") or ("6456099")).PN.                                | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR               | OFF     | 2006/01/29 16:39 |
| L6    | 3    | (US-20040195672-\$ or US-20040197941-\$).did. or (US-6734549-\$).did.   | US-PGPUB;<br>USPAT  | OR               | OFF     | 2006/01/29 16:40 |
| L7    | 2659 | (714/724,726,727).CCLS.   | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR               | OFF     | 2006/01/29 16:40 |
| L8    | 1081 | boundary scan test  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ              | ON      | 2006/01/29 16:40 |
| L9    | 126  | L8 and internal scan  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ              | ON      | 2006/01/29 16:40 |
| L10   | 114  | L9 and (board pcb mount mounting substrate)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/29 16:40 |
| L11   | 86   | L10 and (wire wiring bond bonding)  | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR               | ON      | 2006/01/29 16:40 |
| L12   | 305  | L8 and L7   | US-PGPUB;<br>USPAT;<br>USOCR                                      | ADJ              | OFF     | 2006/01/29 16:40 |
| L13   | 3    | L3 and L8   | US-PGPUB;<br>USPAT;<br>USOCR                                      | ADJ              | ON      | 2006/01/29 16:40 |
| L14   | 2    | L3 and L11  | US-PGPUB;<br>USPAT;<br>USOCR                                      | ADJ              | ON      | 2006/01/29 16:40 |

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|-----|------|---|---|-----|-----|------------------|
| L15 | 1044 | (257/48).CCLS.                                  | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR  | OFF | 2006/01/29 16:40 |
| L16 | 32   | L11 and @pd<"20010702"                          | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR  | ON  | 2006/01/29 16:40 |
| L17 | 71   | L11 and chip                                    | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR  | ON  | 2006/01/29 16:40 |
| L18 | 32   | L16 and @pd<"20010702"                          | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR  | ON  | 2006/01/29 16:40 |
| L19 | 19   | L8 and internal scan chain                      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2006/01/29 16:40 |
| L20 | 16   | L19 and (board pcb mount<br>mounting substrate) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR  | ON  | 2006/01/29 16:40 |
| L21 | 9    | L20 and (wire wiring bond bonding)              | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR  | ON  | 2006/01/29 16:40 |
| L22 | 9    | L21 and input and output                        | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR  | ON  | 2006/01/29 16:40 |
| L23 | 7    | L21 and input terminal and output<br>terminal   | US-PGPUB;<br>USPAT;<br>USOCR                                      | ADJ | ON  | 2006/01/29 16:40 |

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## printed circuit

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A pattern of electrical conductors applied to one or more layers of a substrate (called a printed circuit board or PCB). The conductors electrically interconnect devices physically mounted to the surface(s) of the substrate. (A printed circuit board with components installed is called a *printed circuit assembly*.)

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### Citing this entry

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